



500V N-Channel MOSFET

Pb Lead Free Package and Finish

General Features

- Proprietary New Planar Technology
- $R_{DS(ON),typ.}=0.40\ \Omega@V_{GS}=10V$
- Low Gate Charge Minimize Switching Loss
- Fast Recovery Body Diode

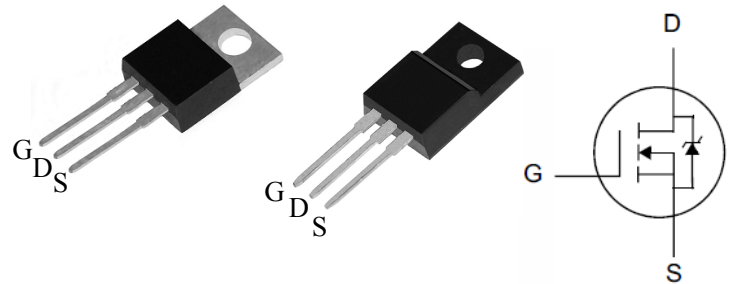
BV_{DSS}	$R_{DS(ON),typ.}$	I_D
500V	0.40Ω	13A

Applications

- ATX Power
- LCD Panel Power

Ordering Information

Part Number	Package	Brand
PTP13N50B	TO-220	
PTA13N50B	TO-220F	



TO-220

TO-220F

Package Not to Scale

Absolute Maximum Ratings

$T_C=25^\circ\text{C}$ unless otherwise specified

Symbol	Parameter	PTP13N50B	PTA13N50B	Unit
V_{DSS}	Drain-to-Source Voltage ^[1]	500		V
V_{GSS}	Gate-to-Source Voltage	±30		
I_D	Continuous Drain Current	13		A
I_{DM}	Pulsed Drain Current at $V_{GS}=10V$ ^[2]	48		
E_{AS}	Single Pulse Avalanche Energy	562		mJ
dv/dt	Peak Diode Recovery dv/dt ^[3]	5.0		V/ns
P_D	Power Dissipation	190	65	W
	Derating Factor above 25°C	1.52	0.52	
T_L T_{PAK}	Maximum Temperature for Soldering Leads at 0.063in (1.6mm) from Case for 10 seconds, Package Body for 10 seconds	300 260		°C
T_J & T_{STG}	Operating and Storage Temperature Range	-55 to 150		

Caution: Stresses greater than those listed in the "Absolute Maximum Ratings" may cause permanent damage to the device.

Thermal Characteristics

Symbol	Parameter	PTP13N50B	PTA13N50B	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	0.66	1.92	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	62	100	



Electrical Characteristics

OFF Characteristics $T_J = 25^\circ\text{C}$ unless otherwise specified

Symbol	Parameter	Min.	Typ.	Max.	Unit	Test Conditions
BV_{DSS}	Drain-to-Source Breakdown Voltage	500	--	--	V	$V_{GS}=0V, I_D=250\mu A$
I_{DSS}	Drain-to-Source Leakage Current	--	--	1	uA	$V_{DS}=500V, V_{GS}=0V$
		--	--	100		$V_{DS}=400V, V_{GS}=0V, T_J=125^\circ\text{C}$
I_{GSS}	Gate-to-Source Leakage Current	--	--	+100	nA	$V_{GS}=+30V, V_{DS}=0V$
		--	--	-100		$V_{GS}=-30V, V_{DS}=0V$

ON Characteristics

$T_J = 25^\circ\text{C}$ unless otherwise specified

Symbol	Parameter	Min.	Typ.	Max.	Unit	Test Conditions
$R_{DS(ON)}$	Static Drain-to-Source On-Resistance ^[4]	--	0.40	0.50	Ω	$V_{GS}=10V, I_D=6.0A$
$V_{GS(TH)}$	Gate Threshold Voltage	2.0	--	4.0	V	$V_{DS}=V_{GS}, I_D=250\mu A$
gfs	Forward Transconductance ^[4]	--	20	--	S	$V_{DS}=20V, I_D=13A$

Dynamic Characteristics

Essentially independent of operating temperature

Symbol	Parameter	Min.	Typ.	Max.	Unit	Test Conditions
C_{iss}	Input Capacitance	--	1180	--	pF	$V_{GS}=0V, V_{DS}=25V, f=1.0\text{MHz}$
C_{rSS}	Reverse Transfer Capacitance	--	13	--		
C_{oss}	Output Capacitance	--	120	--		
Q_g	Total Gate Charge	--	32	--	nC	$V_{DD}=400V, I_D=13A, V_{GS}=0 \text{ to } 10V$
Q_{gs}	Gate-to-Source Charge	--	7	--		
Q_{gd}	Gate-to-Drain (Miller) Charge	--	16	--		

Resistive Switching Characteristics

Essentially independent of operating temperature

Symbol	Parameter	Min.	Typ.	Max.	Unit	Test Conditions
$t_{d(ON)}$	Turn-on Delay Time	--	21	--	nS	$V_{DD}=250V, I_D=13A, V_{GS}=10V, R_G=25\Omega$
t_{rise}	Rise Time	--	13	--		
$t_{d(OFF)}$	Turn-Off Delay Time	--	88	--		
t_{fall}	Fall Time	--	30	--		



Source-Drain Body Diode Characteristics

$T_J=25^{\circ}\text{C}$ unless otherwise specified

Symbol	Parameter	Min	Typ.	Max.	Unit	Test Conditions
I_{SD}	Continuous Source Current ^[4]	--	--	13	A	Integral PN-diode in MOSFET
I_{SM}	Pulsed Source Current ^[4]	--	--	48		
V_{SD}	Diode Forward Voltage	--	--	1.4	V	$I_S=13\text{A}$, $V_{GS}=0\text{V}$
trr	Reverse recovery time	--	310	--	ns	$V_{GS}=0\text{V}$, $I_F=13\text{A}$, $di_F/dt=100\text{A}/\mu\text{s}$
Qrr	Reverse recovery charge	--	4.0	--	uC	

Note:

[1] $T_J=+25^{\circ}\text{C}$ to $+150^{\circ}\text{C}$

[2] Repetitive rating; pulse width limited by maximum junction temperature.

[3] $I_{SD}=13\text{A}$, $di/dt < 100\text{A}/\mu\text{s}$, $V_{DD} < BV_{DSS}$, $T_J=+150^{\circ}\text{C}$.

[4] Pulse width $\leq 380\mu\text{s}$; duty cycle $\leq 2\%$.



Typical Characteristics

Figure 1. Output Characteristics ($T_J = 25^\circ\text{C}$)

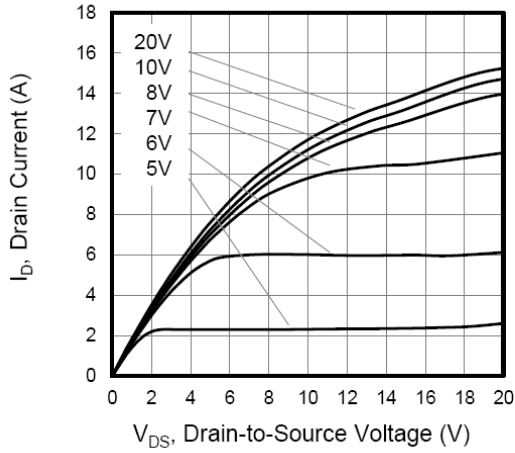


Figure 2. Body Diode Forward Voltage

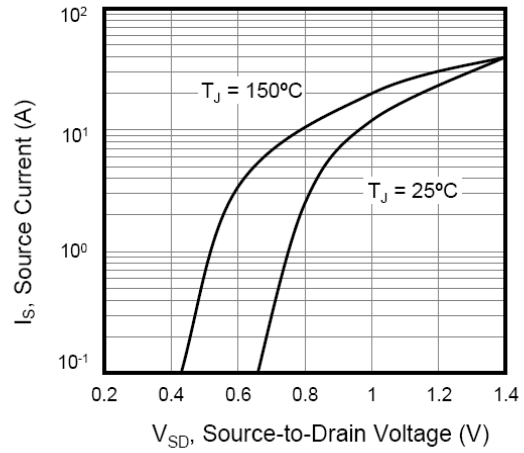


Figure 3. Drain Current vs. Temperature

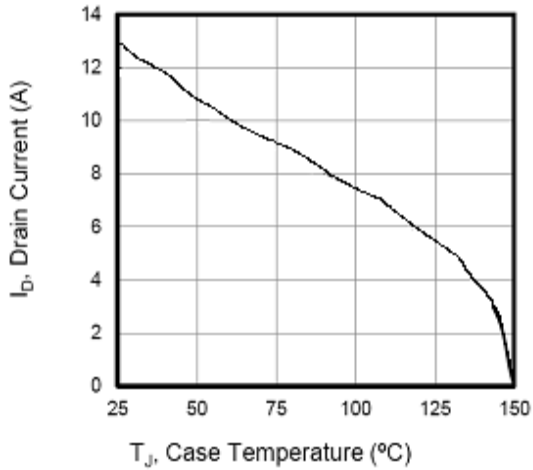


Figure 4. BV_{DSS} Variation vs. Temperature

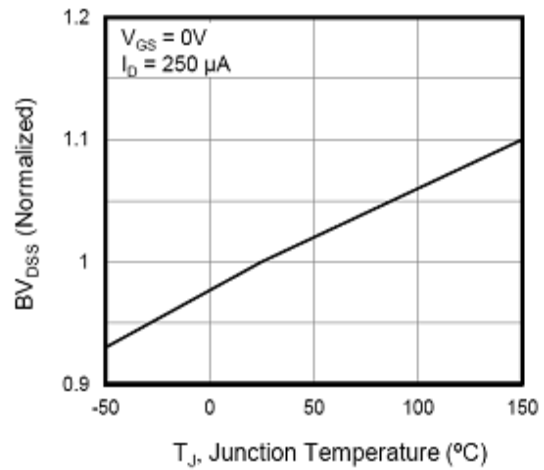


Figure 5. Transfer Characteristics

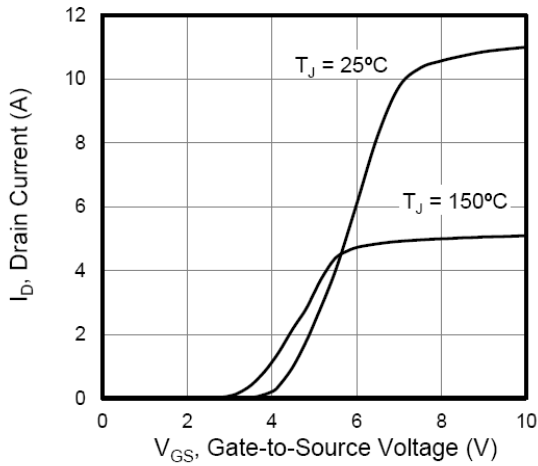
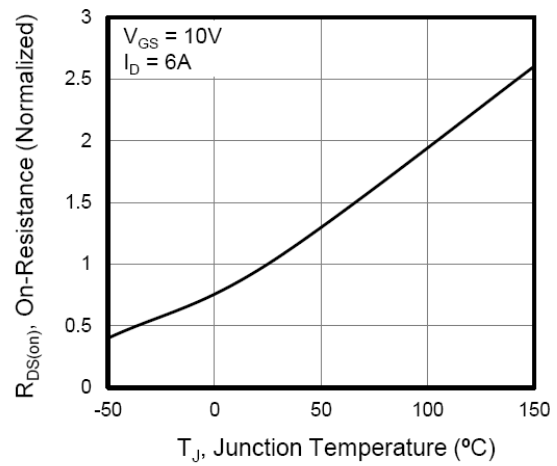


Figure 6. On-Resistance vs. Temperature





Typical Characteristics(Cont.)

Figure 7. Capacitance

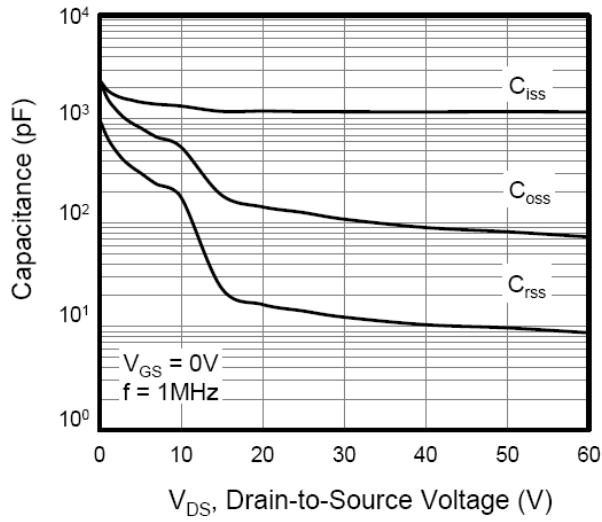


Figure 8. Gate Charge

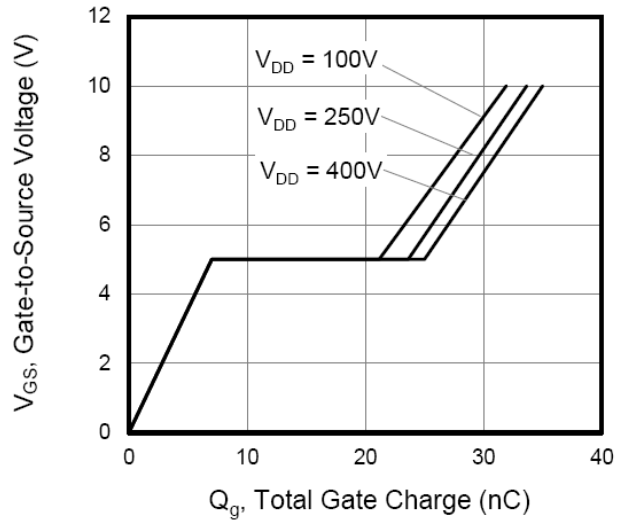
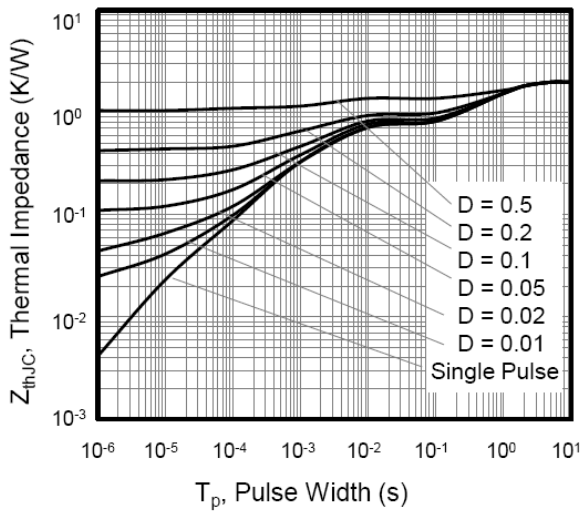


Figure 9. Transient Thermal Impedance





Test Circuits and Waveforms

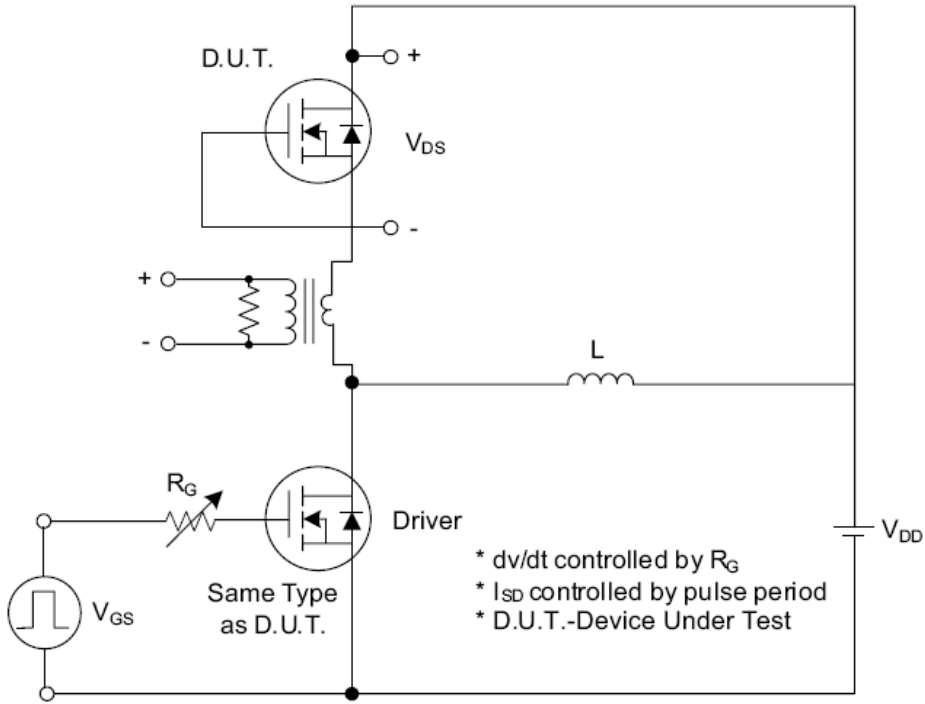


Fig. 1.1 Peak Diode Recovery dv/dt Test Circuit

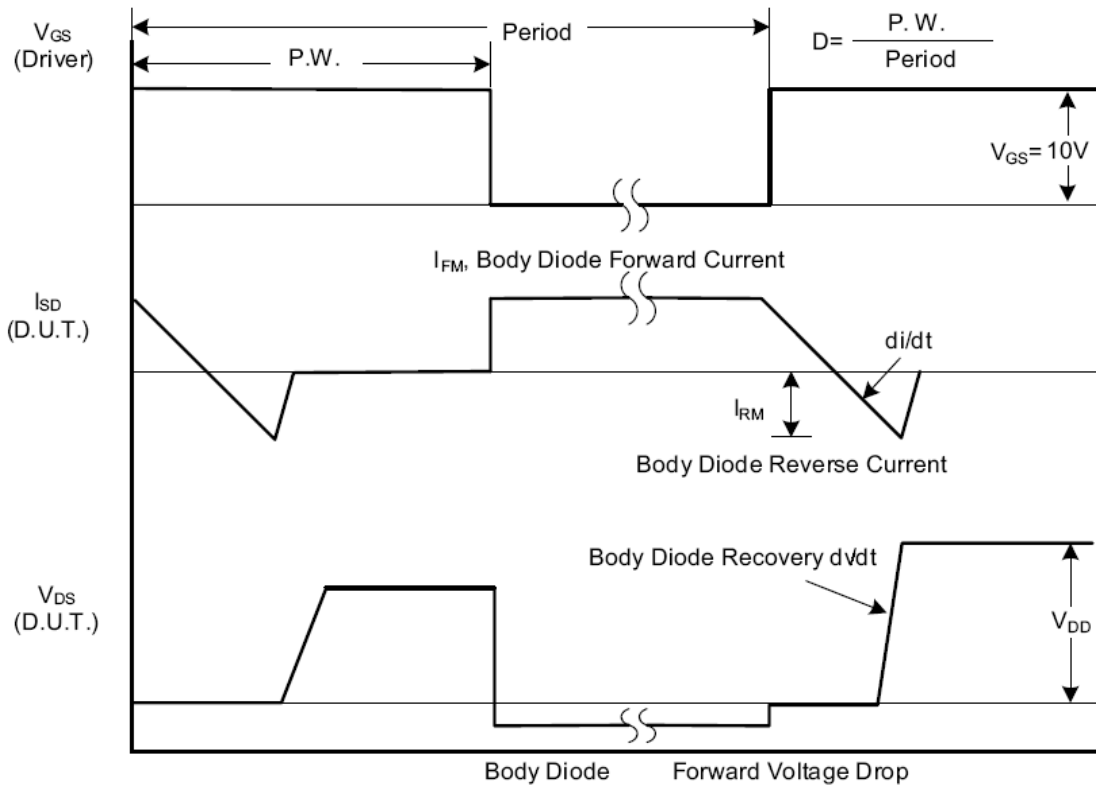


Fig. 1.2 Peak Diode Recovery dv/dt Waveforms



Test Circuits and Waveforms (Cont.)

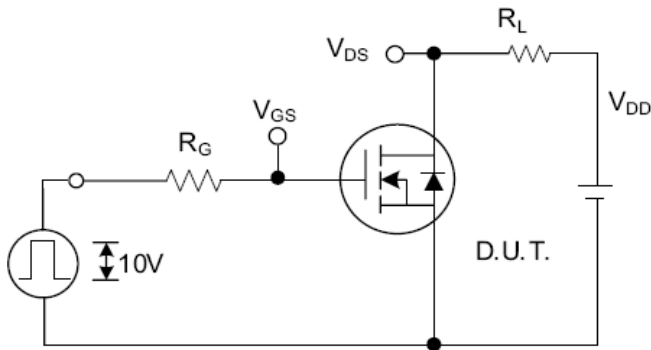


Fig. 2.1 Switching Test Circuit

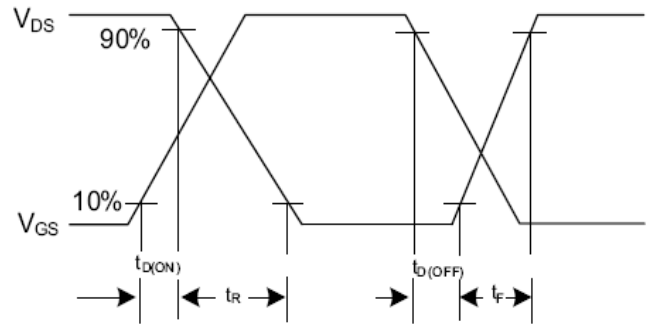


Fig. 2.2 Switching Waveforms

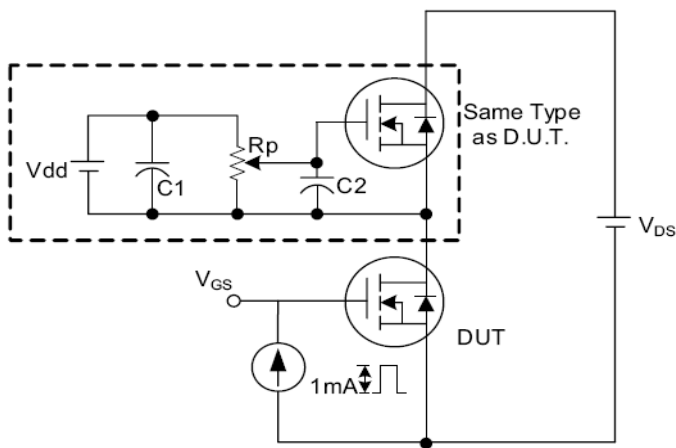


Fig. 3.1 Gate Charge Test Circuit

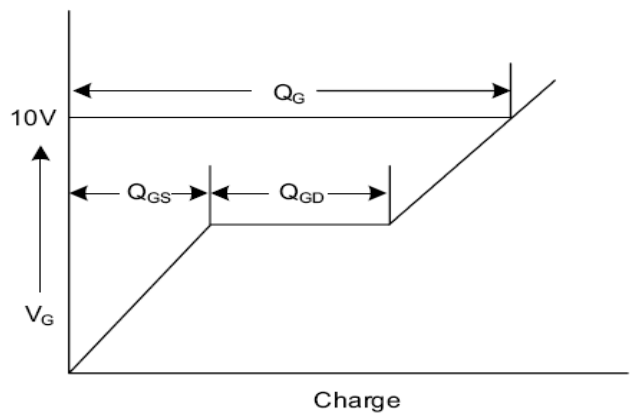


Fig. 3.2 Gate Charge Waveform

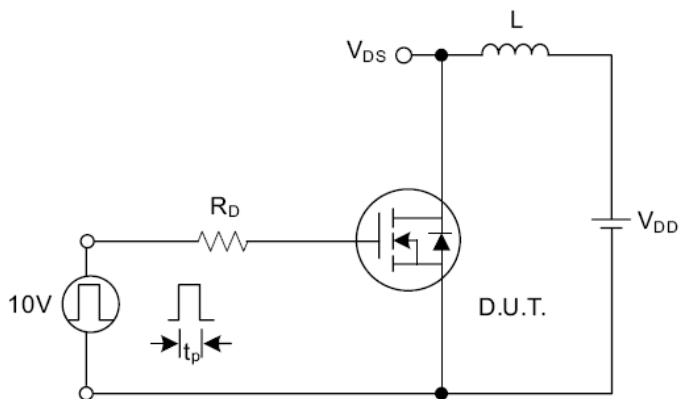


Fig. 4.1 Unclamped Inductive Switching Test Circuit

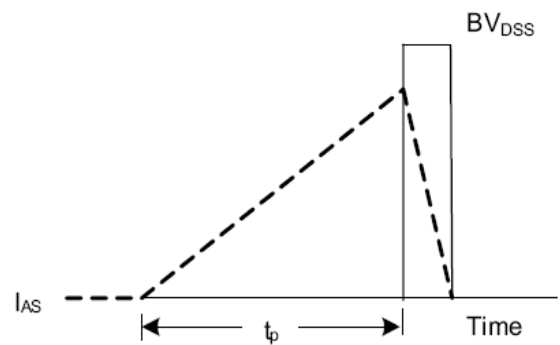


Fig. 4.2 Unclamped Inductive Switching Waveforms



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